

L Number	Hits	Search Text	DB	Time stamp
1	415	257/706 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:15
2	481	257/433 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:20
3	301	257/707 and (laser or "LED" or light near emit\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:24
4	253	(257/712 or 257/713 or 257/714) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:31
5	101	(257/715 or 257/716 or 257/717) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:31
6	139	(257/718 or 257/719 or 257/720 or 257/721) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:34
7	920	(385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:47
8	1052	(semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:49
9	839	((semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)) not ((385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:50
10	804	((semiconductor or die or chip or IC) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43) with (double or dual or both or multi\$4 or second)) not (((385/88 or 438/122 or 372/36) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)) or (257/706 and (laser or "LED" or light near emit\$3)) or (257/433 and (laser or "LED" or light near emit\$3)) or (257/707 and (laser or "LED" or light near emit\$3)) or ((257/712 or 257/713 or 257/714) and (laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane or spreader or stiffener or transfer or dissipat43)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 23:50
-	1	5454002.pn./	USPAT	2004/04/28 03:48

-	1	5454002.pn. and isolat\$3 with attach\$3	USPAT	2004/04/28 04:12
-	1	(light near emitting near device) and	USPAT	2004/04/28 04:38
-	0	adhesive with solder with heat near sink	USPAT	2004/04/28 04:38
-	0	(light near emitting near device) and	USPAT	2004/04/28 04:38
-	0	adhesive with heat near sink with second	USPAT	2004/04/28 04:38
-	0	near heat	USPAT	2004/04/28 04:39
-	6	(light near emitting near device or laser	USPAT	2004/04/28 04:43
-	0	or LED) and adhesive with solder with heat	USPAT	2004/04/28 04:44
-	6	near sink with second near heat	USPAT	2004/04/28 04:44
-	0	(light near emitting near device or laser	USPAT	2004/04/28 04:46
-	6	or LED) and adhesive with heat near sink	USPAT	2004/04/28 04:46
-	337	with stiffener	USPAT	2004/04/28 04:49
-	81	(light near emitting near device or laser	USPAT	2004/04/28 04:52
-	3	or LED) and adhesive with heat near sink	USPAT	2004/04/28 04:52
-		with heat) and adhesive with heat near		
-		sink with heat and adhesive with solder		
-		((light near emitting near device or laser		
-		or LED) and adhesive with heat near sink		
-		with heat) and adhesive with heat near		
-		sink with heat and adhesive with solder		
-		and ("AuGe" or "PbSn")		